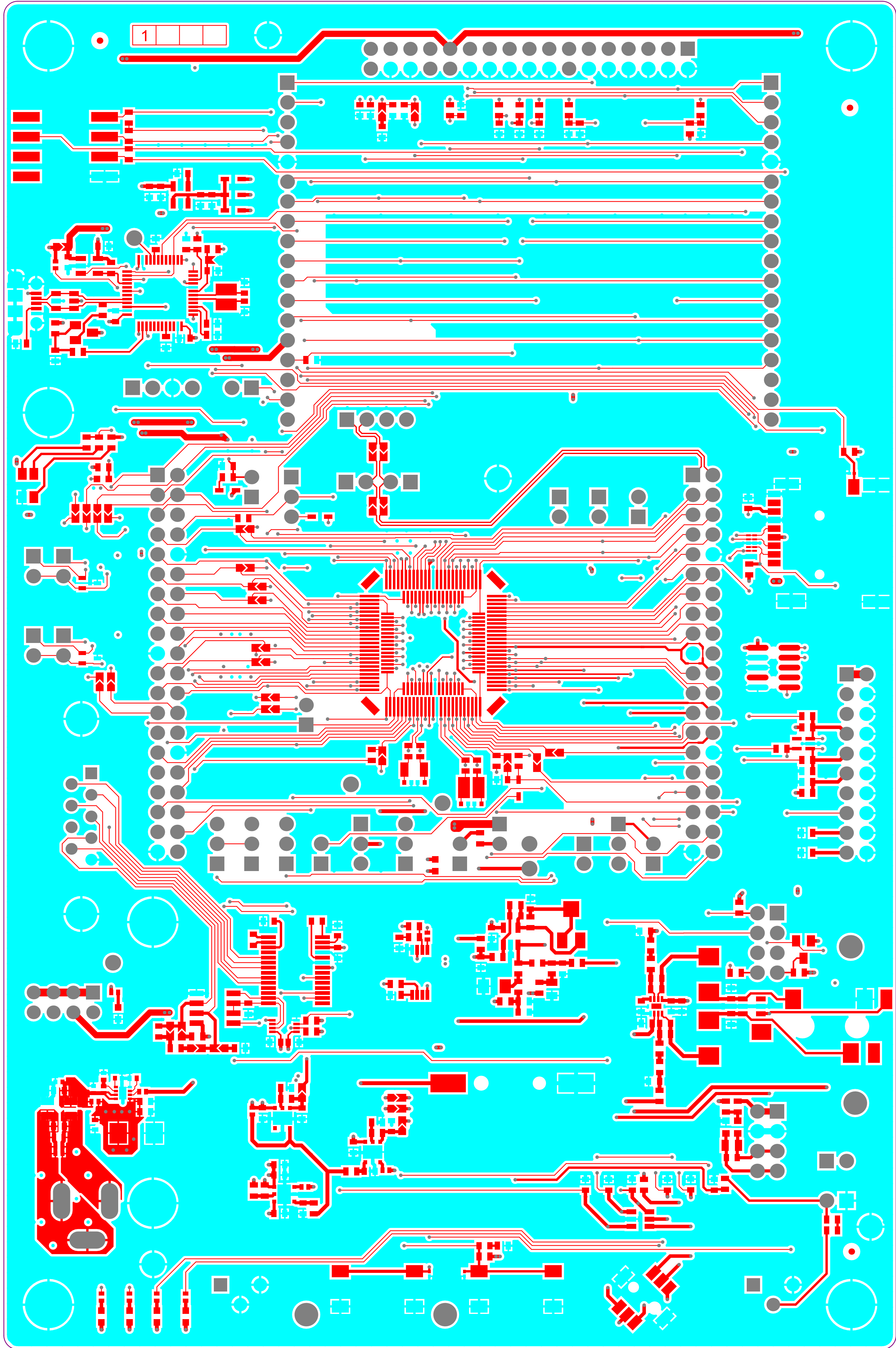


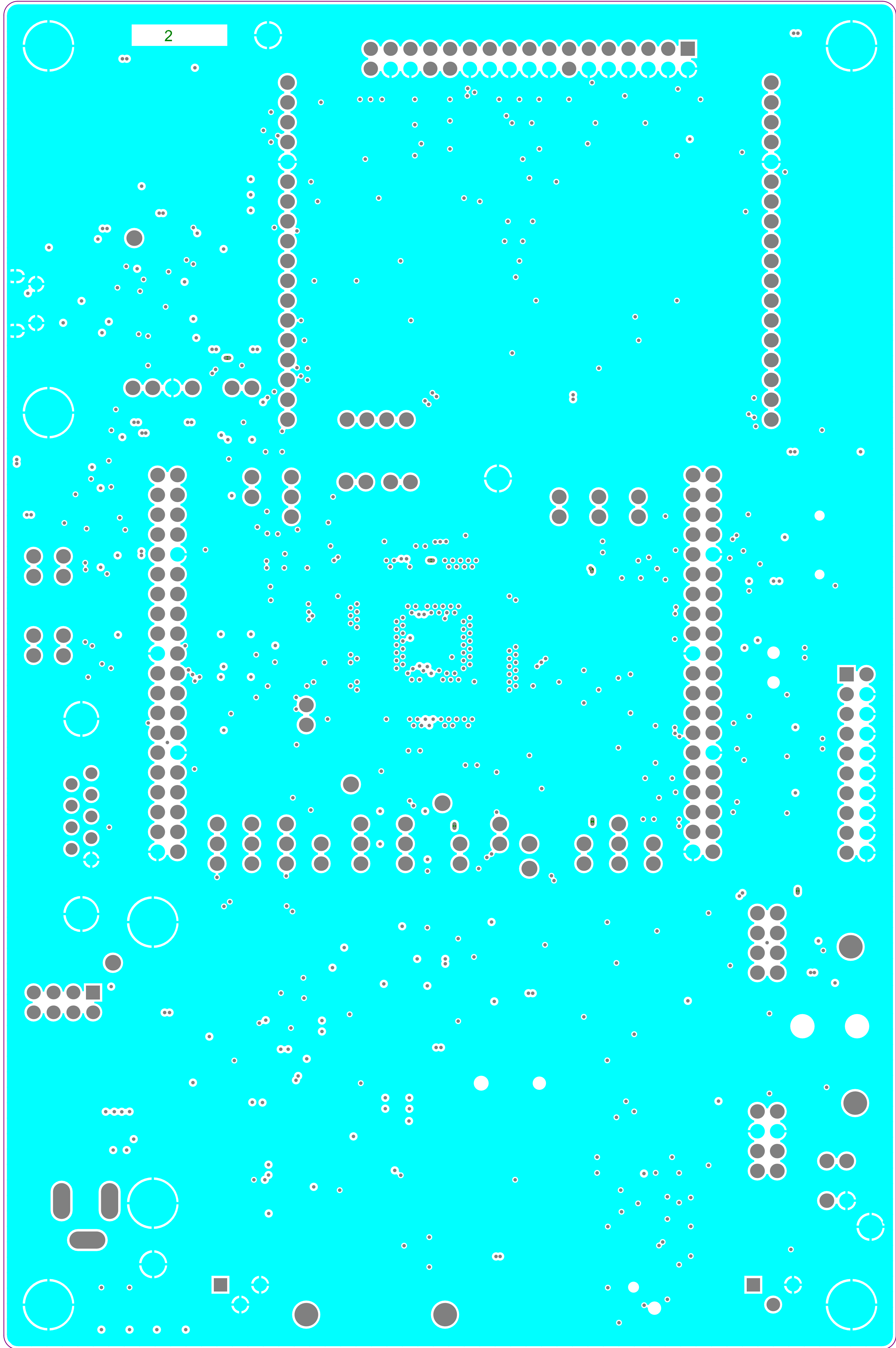
Project: STM32G0C1E-EV	
Layer: Top Solder	Gerber: .GTS
Variant: [No Variations]	Ref: MB1581
Date: 17-JUN-2020	Rev: B





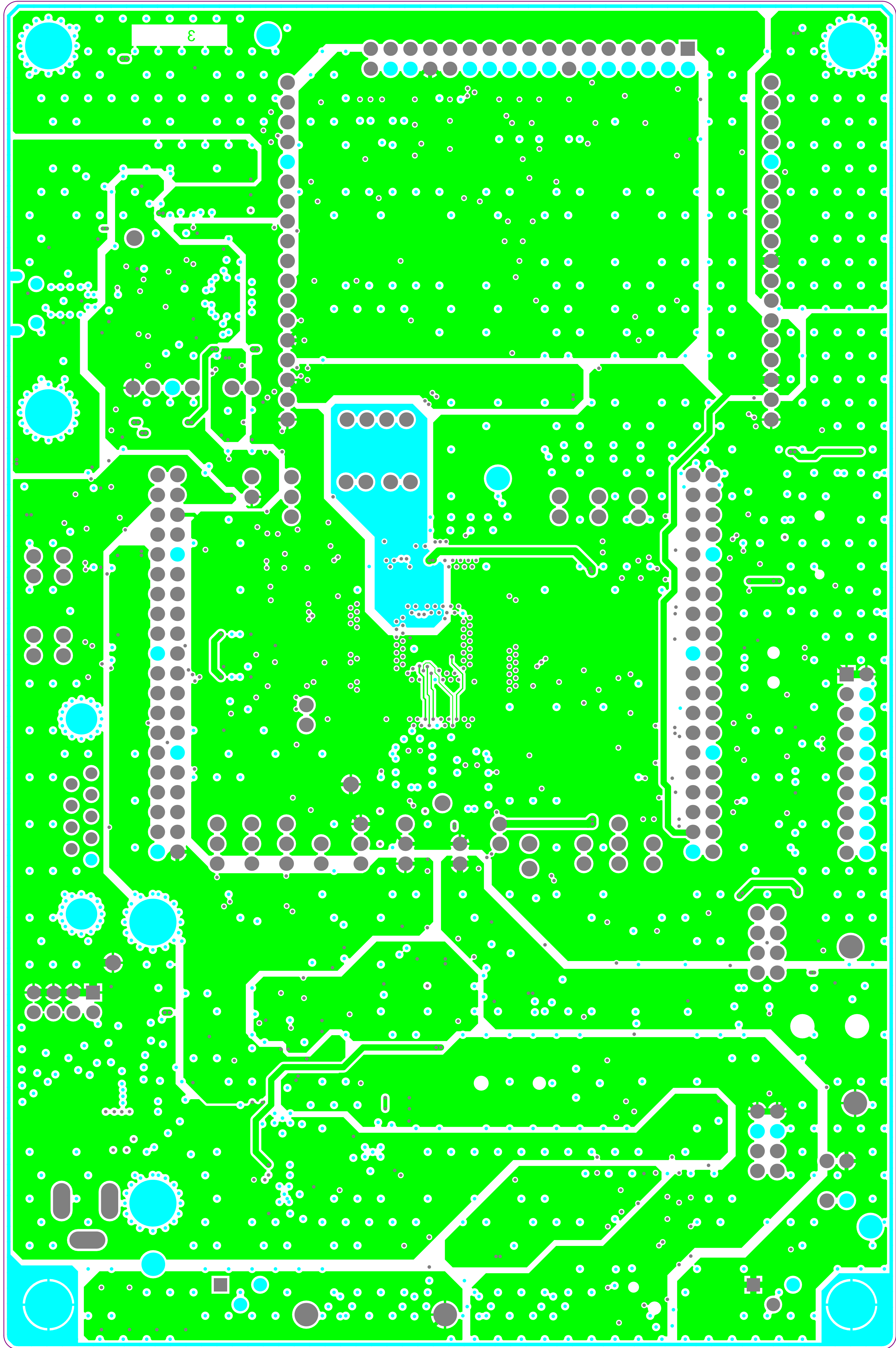
Project: STM32G0C1E-EV	
Layer: Top Layer	Gerber: .GTL
Variant: [No Variations]	Ref: MB1581
Date: 17-JUN-2020	Rev: B





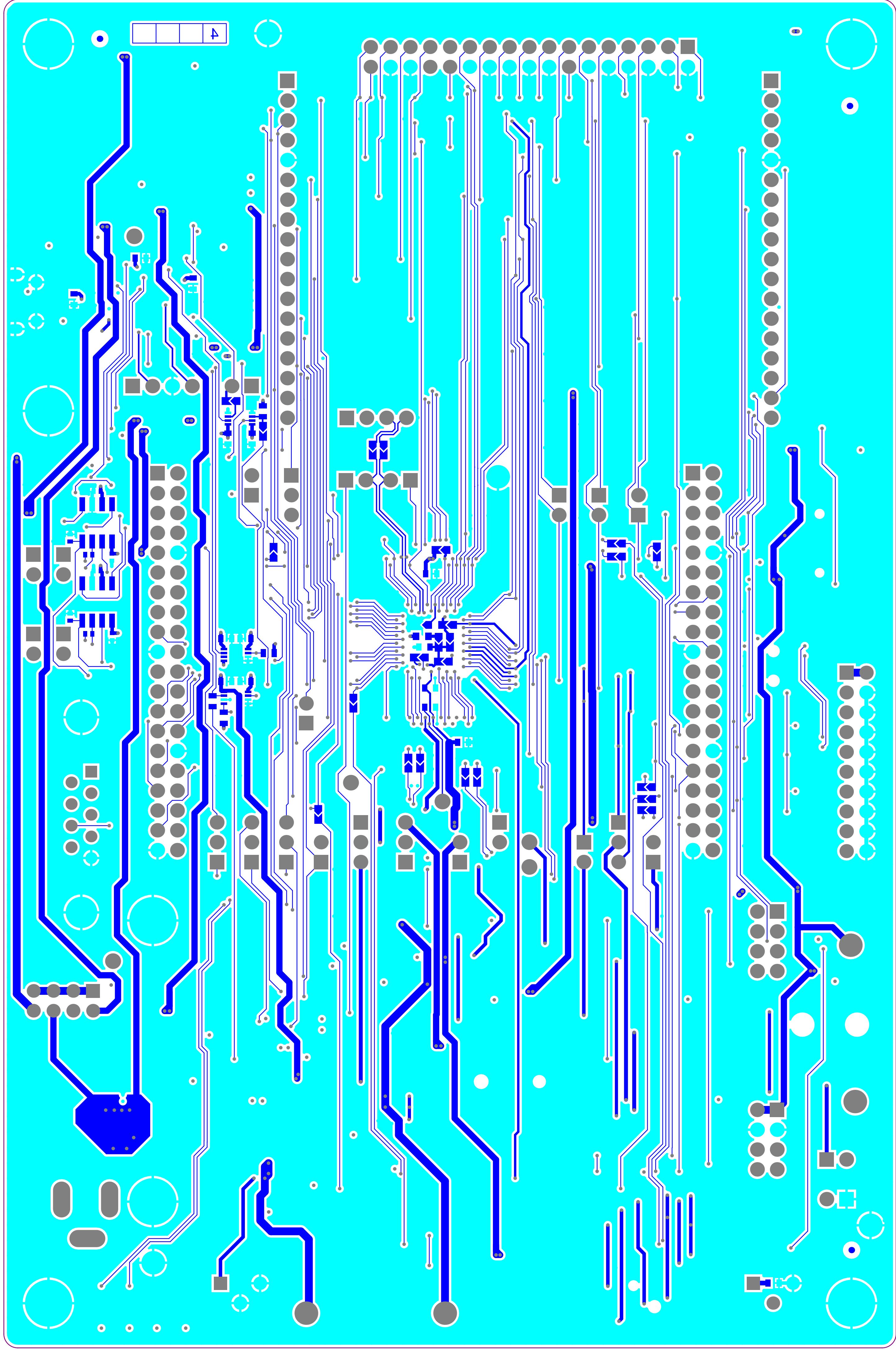
Project: STM32G0C1E-EV	
Layer: Signal Layer 1	Gerber: .G1
Variant: [No Variations]	Ref: MB1581
Date: 17-JUN-2020	Rev: B



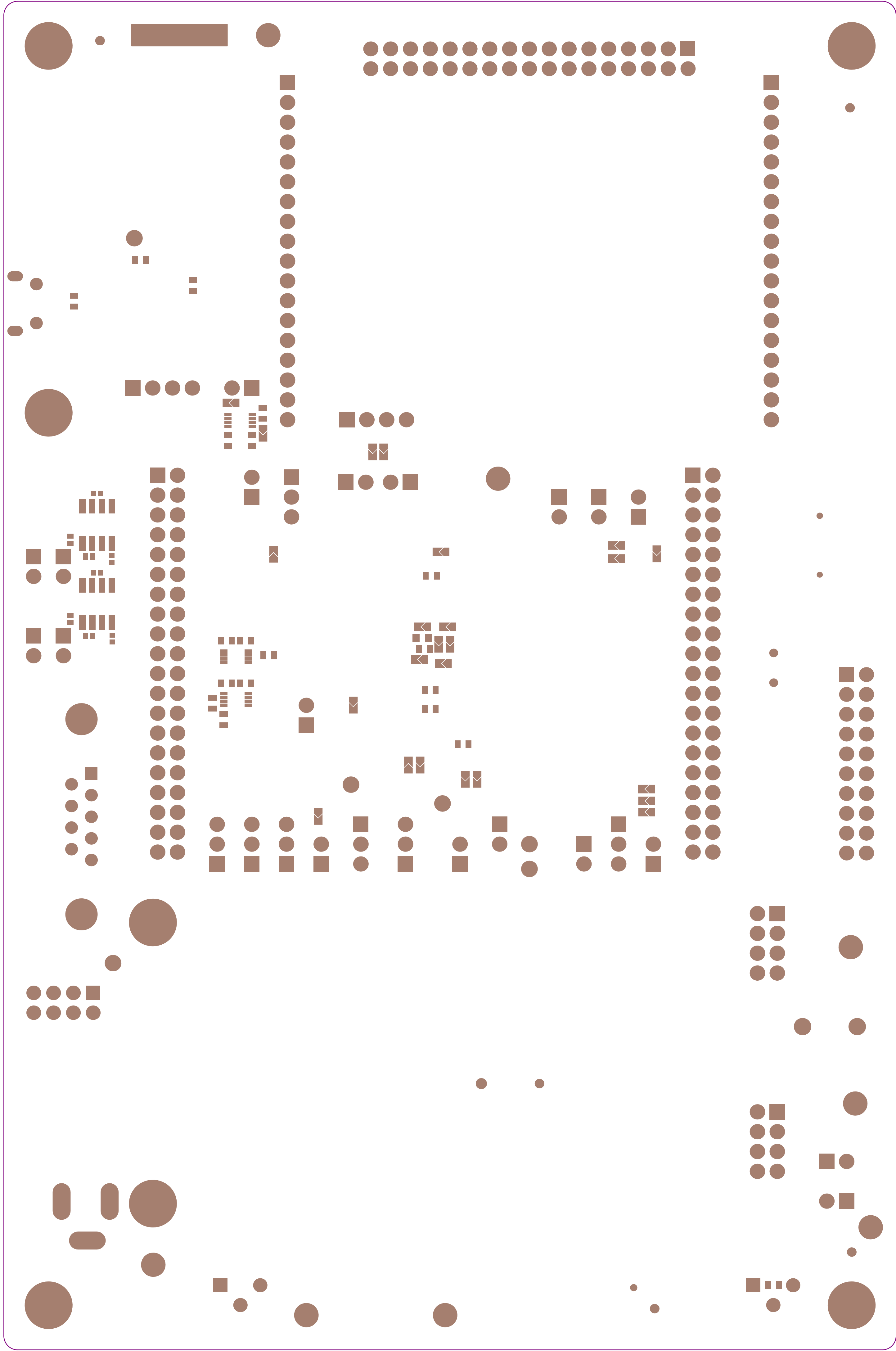


Project: STM32G0C1E-EV	
Layer: Signal Layer 2	Gerber: .G2
Variant: [No Variations]	Ref: MB1581
Date: 17-JUN-2020	Rev: B



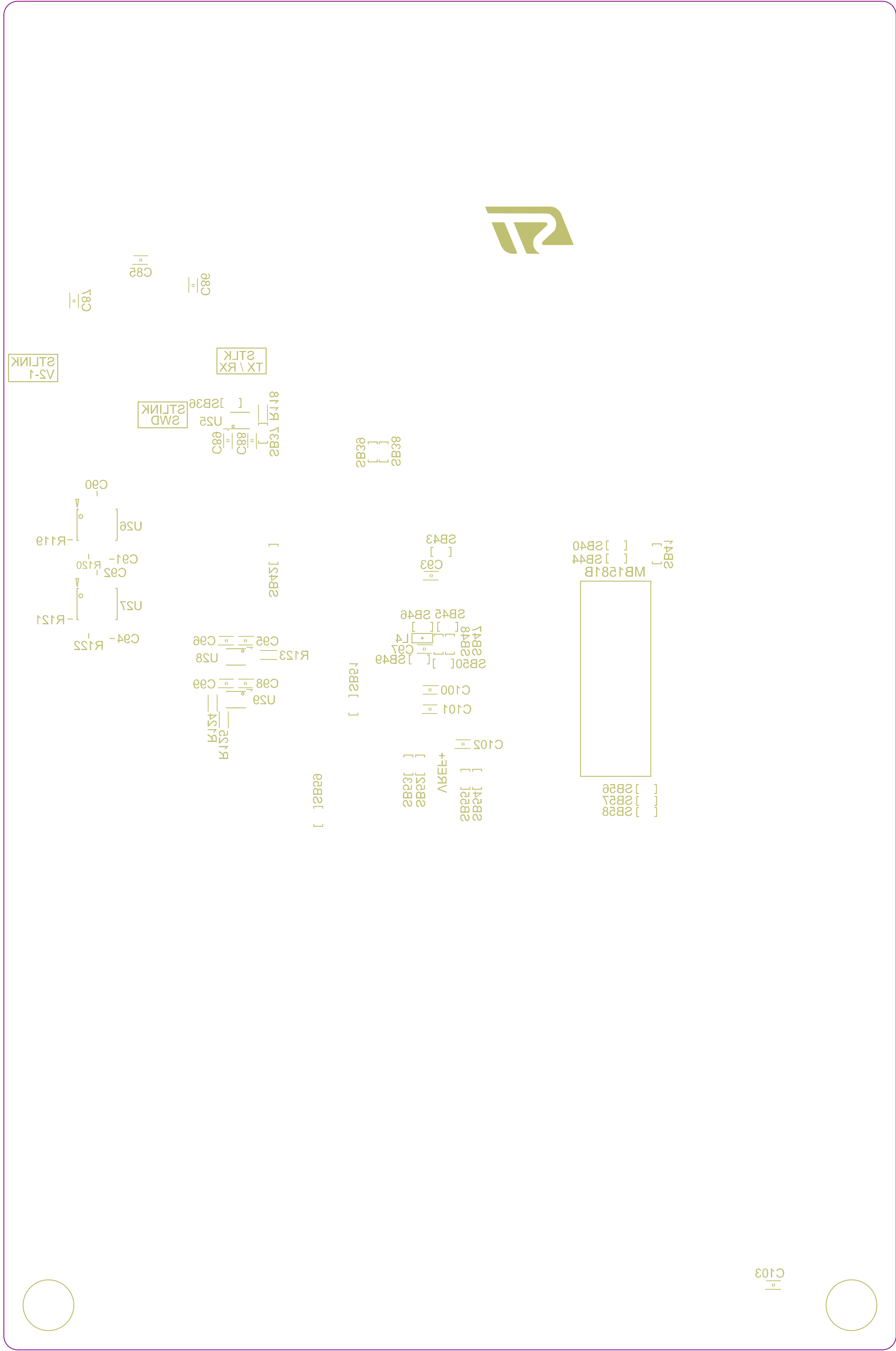


	Date: 17-JUN-2020		Rev: B	Variant: [No Variations]	Ref: MB1581	Layer: Bottom Layer	Gerber: GBL	Project: STM32G0C1E-EV
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Date: 17-JUN-2020			Rev: B
Variant: [No Variations]			Ref: MB1581
Layer: Bottom Solder			Gerber: GBS
Project: STM32G0C1E-EV			

®



THE COMPONENTS WITH PLATED THROUGH HOLE (PTH) MAY BE WELDED (CABLED) IN "PIN-IN-PASTE" MODE
(IF NECESSARY), ON BOTTOM LAYER (4)

PCB SPECIFICATIONS :

A. MATERIAL :

B. MATERIAL FAMILY :

C. SOLDERMASK COLOR :

D. SILKSCREEN COLOR :

E. SURFACE FINISH :

F. IMPEDANCE CONTROL :

G. THROUGH VIA :

H. STACK-UP :

FR-4

N/A

☐ GREEN

☐ WHITE

☐ RED

☒ BLUE

☒ WHITE

☐ YELLOW

☐ BLACK

☐ Blue ink PANTONE 2955

☒ ENIG

☐ IMMERSION SILVER

☐ IMMERSION TIN

☐ HASL

☐ HASL (PB-FREE)

☐ GOLDEN FINGER

☐ NO

☒ YES (SEE IMPEDANCE TABLE FOR DETAIL INFORMATION)

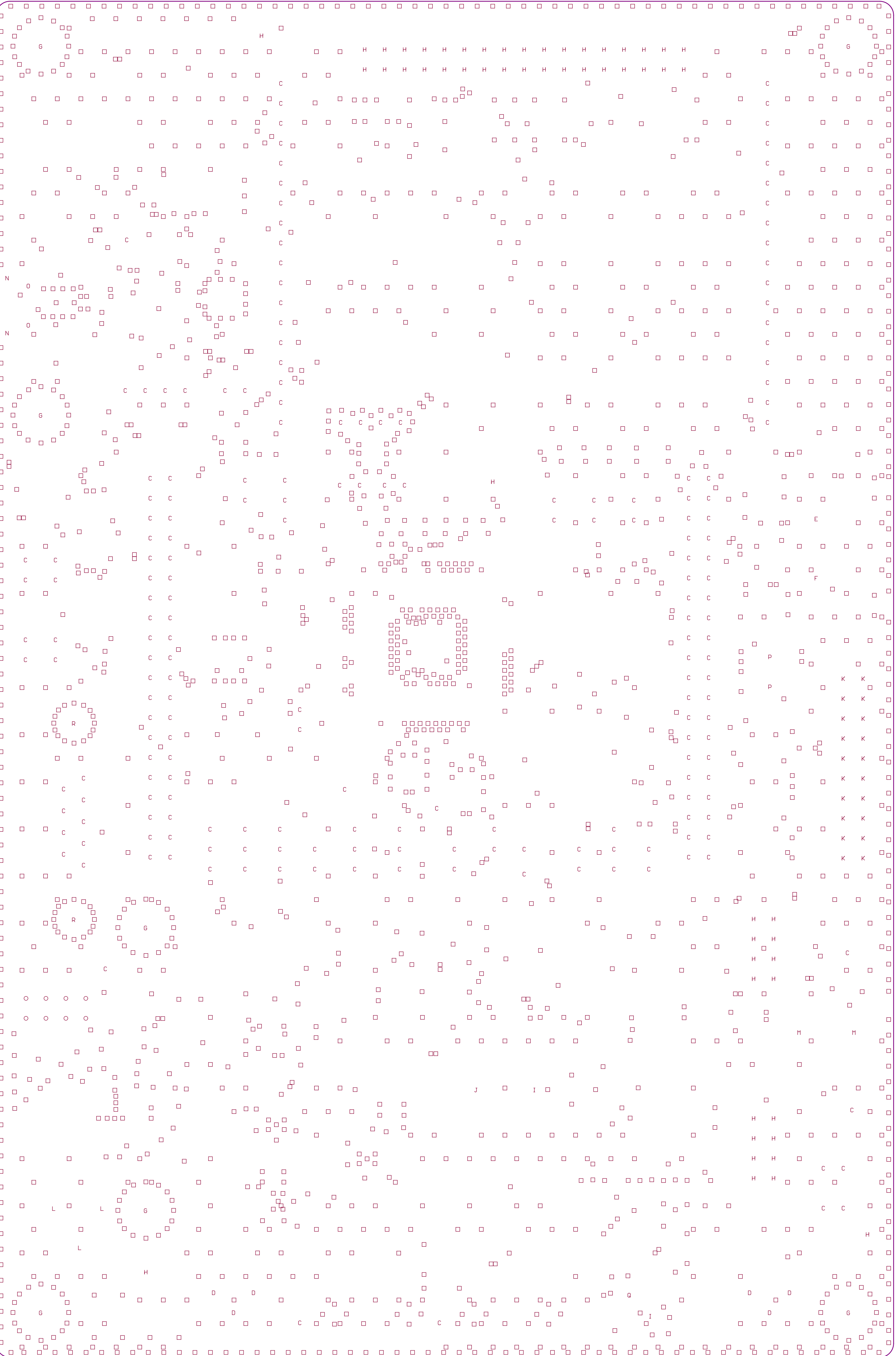
PLUG THE VIAS WHICH ARE COVERED WITH SOLDERMASK ONE OR TWO SIDE.
PLUG MATERIAL : ☒ SOLDERMASK ☐ NON-CONDUCTIVE EPOXY.
SEE LAYER STACK-UP SEQUENCE FOR OVERALL THICKNESS.

PCB : TYPE 3

ASPECT-RATIO, AXE Z :
6:1 to 8:1
LEVEL "B"

MINIMUM PARAMETERS

DEFAULT
TRACKS : 0.100mm
GAPS : 0.150mm



Layer	Name	Material	Thickness	Constant	Board Layer Stack
1	Top Overlay				
2	Top Solder	Solder Resist	0,015mm	3,5	
3	Top Layer	Copper	0,042mm		
4	Dielectric 1	TU-768P 3313H	0,100mm	4,05	
5	Signal Layer 1	Copper	0,035mm		
6	Dielectric 2	TU-768 1.3	1,230mm	4,05	
7	Signal Layer 2	Copper	0,035mm		
8	Dielectric 3	TU-768P 3313H	0,100mm	4,05	
9	Bottom Layer	Copper	0,042mm		
10	Bottom Solder	Solder Resist	0,015mm	3,5	
11	Bottom Overlay				

Symbol	Count	Hole Size	Plated	Hole Type	Drill Layer Pair	Via/Pad	Hole Length	Routed Path Length
	2024	0,200mm (7,87mil)	PTH	Round	Top Layer - Bottom Layer	Via	-	-
N	2	0,600mm (23,62mil)	PTH	Slot	Top Layer - Bottom Layer	Pad	1,300mm (51,18mil)	0,700mm (27,56mil)
F	1	0,650mm (25,59mil)	NPTH	Round	Top Layer - Bottom Layer	Pad	-	-
E	1	0,700mm (27,56mil)	NPTH	Round	Top Layer - Bottom Layer	Pad	-	-
Q	1	0,800mm (31,50mil)	NPTH	Round	Top Layer - Bottom Layer	Pad	-	-
D	6	0,800mm (31,50mil)	PTH	Round	Top Layer - Bottom Layer	Pad	-	-
O	2	0,900mm (35,43mil)	PTH	Round	Top Layer - Bottom Layer	Pad	-	-
P	2	1,000mm (39,37mil)	NPTH	Round	Top Layer - Bottom Layer	Pad	-	-
C	202	1,000mm (39,37mil)	PTH	Round	Top Layer - Bottom Layer	Pad	-	-
L	3	1,000mm (39,37mil)	PTH	Slot	Top Layer - Bottom Layer	Pad	3,500mm (137,80mil)	2,500mm (98,43mil)
O	8	1,050mm (41,34mil)	PTH	Round	Top Layer - Bottom Layer	Pad	-	-
I	2	1,100mm (43,31mil)	NPTH	Round	Top Layer - Bottom Layer	Pad	-	-
H	54	1,100mm (43,31mil)	PTH	Round	Top Layer - Bottom Layer	Pad	-	-
K	20	1,200mm (47,24mil)	PTH	Round	Top Layer - Bottom Layer	Pad	-	-
J	1	1,300mm (51,18mil)	NPTH	Round	Top Layer - Bottom Layer	Pad	-	-
M	2	2,000mm (78,74mil)	NPTH	Round	Top Layer - Bottom Layer	Pad	-	-
R	2	3,300mm (129,92mil)	PTH	Round	Top Layer - Bottom Layer	Pad	-	-
G	7	3,500mm (137,80mil)	PTH	Round	Top Layer - Bottom Layer	Pad	-	-
	2340 Total							

Slot definitions : Routed Path Length = Calculated from tool start centre position to tool end centre position.
Hole Length = Routed Path Length + Tool Size = Slot length as defined in the PCB layout

Project: STM32G0C1E-EV

Layer: Drill Drawing

Variant: [No Variations]

Date: 17-JUN-2020

Gerber: .DRL

Ref: MB1581

Rev: B